Yue Zhang

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/10406714/publications.pdf

Version: 2024-02-01

12	210	6	6
papers	citations	h-index	g-index

1478505 1872680

13	13	13	169
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Thermal Isolation Using Air Gap and Mechanically Flexible Interconnects for Heterogeneous 3-D ICs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 31-39.	2.5	13
2	Fabrication and Characterization of Electrical Interconnects and Microfluidic Cooling for 3D ICS With Silicon Interposer. Heat Transfer Engineering, 2016, 37, 903-911.	1.9	6
3	Thermal Design and Constraints for Heterogeneous Integrated Chip Stacks and Isolation Technology Using Air Gap and Thermal Bridge. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 1914-1924.	2.5	45
4	Thermal and electrical effects of staggered micropin-fin dimensions for cooling of 3D microsystems. , 2014, , .		18
5	Tier-independent microfluidic cooling for heterogeneous 3D ICs with nonuniform power dissipation. , 2013, , .		3
6	3-D Stacked Tier-Specific Microfluidic Cooling for Heterogeneous 3-D ICs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 1811-1819.	2.5	24
7	Silicon Micropin-Fin Heat Sink With Integrated TSVs for 3-D ICs: Tradeoff Analysis and Experimental Testing. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 1842-1850.	2.5	38
8	Independent interlayer microfluidic cooling for heterogeneous 3D IC applications. Electronics Letters, 2013, 49, 404-406.	1.0	24
9	Within-tier cooling and thermal isolation technologies for heterogeneous 3D ICs. , 2013, , .		18
10	Design, fabrication and assembly of a novel electrical and microfluidic I/Os for 3-D chip stack and silicon interposer. , 2013, , .		3
11	High aspect ratio TSVs in micropin-fin heat sinks for 3D ICs. , 2012, , .		8
12	Fine pitch TSV integration in silicon micropin-fin heat sinks for 3D ICs. , 2012, , .		9